

## N-Ch 60V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



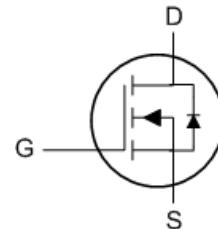
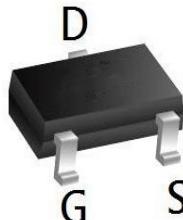
BVDSS	RDS(on)	ID
60V	75 mΩ	3 A

## Description

The XR6003L is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(on) and efficiency for most of the small power switching and load switch applications.

The XR6003L meet the RoHS and Green Product requirement with full function reliability approved.

## SOT23-3L Pin Configuration

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	3	A
		$T_A = 100^\circ\text{C}$	2	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		12	A
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	1.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		83	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

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Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise specified)

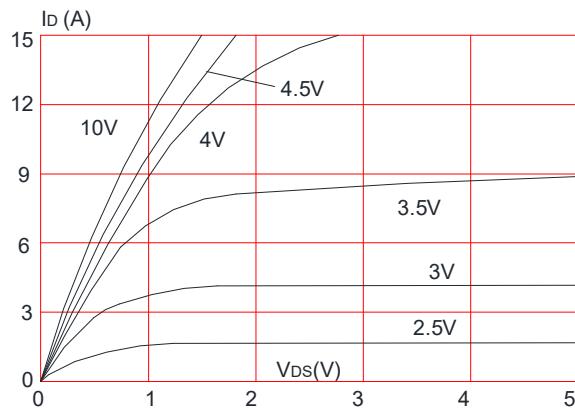
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	1.0	1.4	2.0	V
$R_{\text{DS}(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=3\text{A}$	-	75	100	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=2\text{A}$	-	85	120	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	350	-	pF
$C_{\text{oss}}$	Output Capacitance		-	29	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	23	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=30\text{V}$ , $I_D=3\text{A}$ , $V_{\text{GS}}=10\text{V}$	-	9	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	1.5	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	2	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}$ , $I_D=2\text{A}$ , $R_{\text{GEN}}=3\Omega$ , $V_{\text{GS}}=10\text{V}$	-	5	-	ns
$t_r$	Turn-on Rise Time		-	7	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	37	-	ns
$t_f$	Turn-off Fall Time		-	22	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	3	A	
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	12	A	
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$ , $I_s=3\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

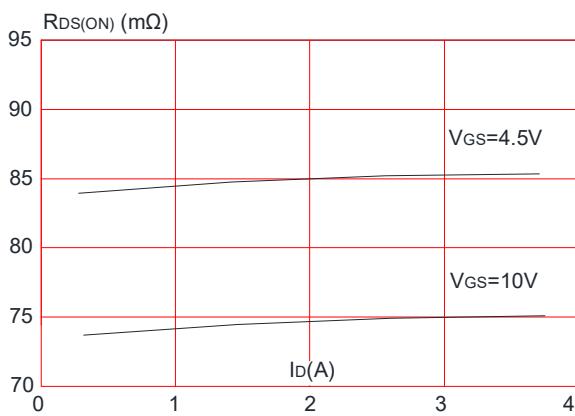
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

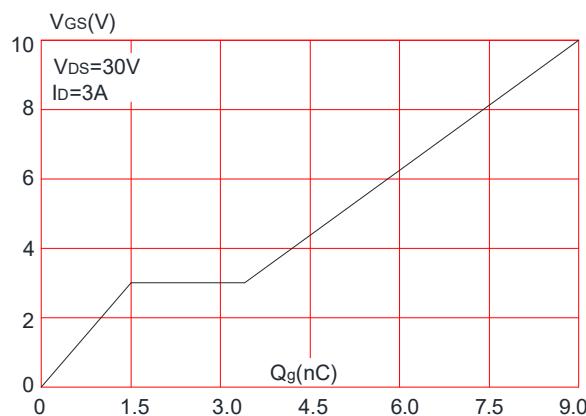
**Figure 1:** Output Characteristics



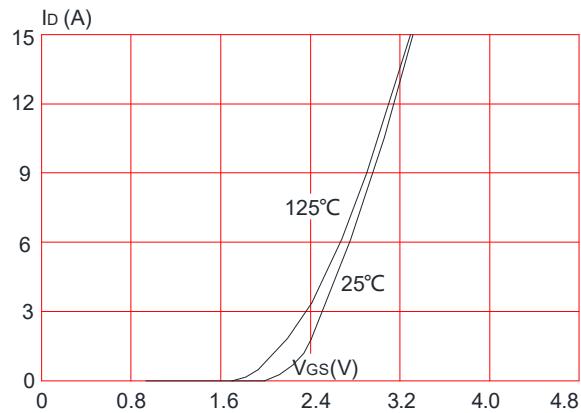
**Figure 3:** On-resistance vs. Drain Current



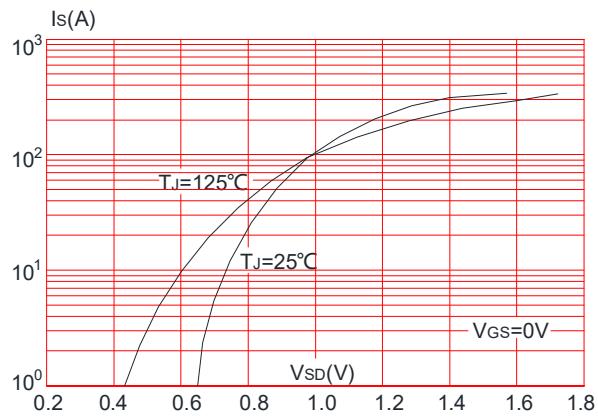
**Figure 5:** Gate Charge Characteristics



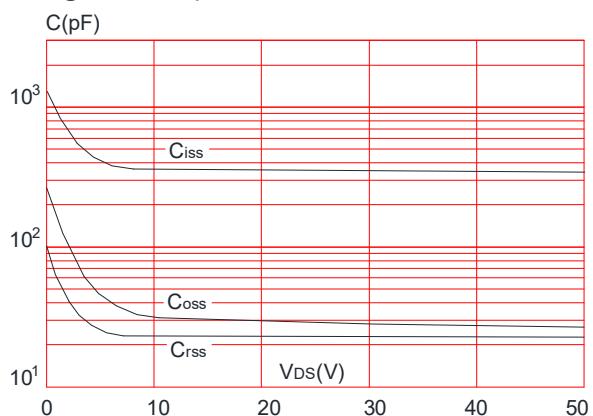
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics

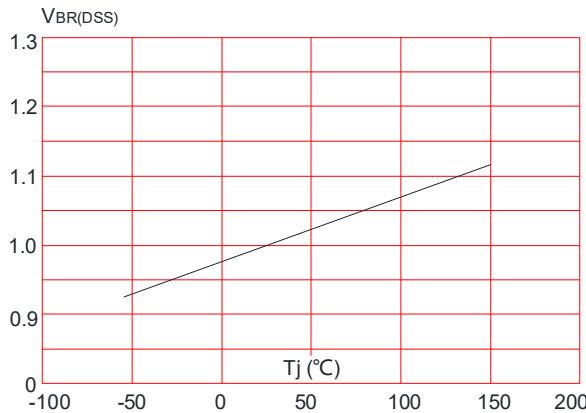


**Figure 6:** Capacitance Characteristics

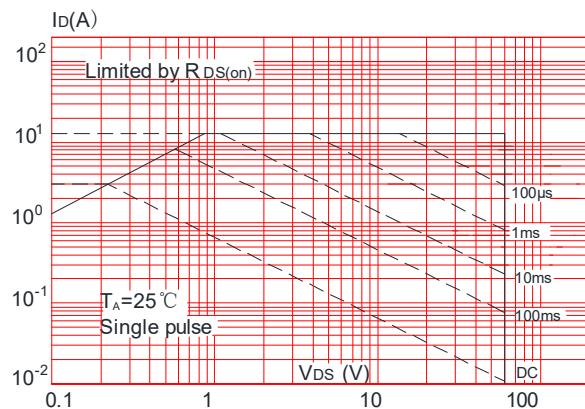


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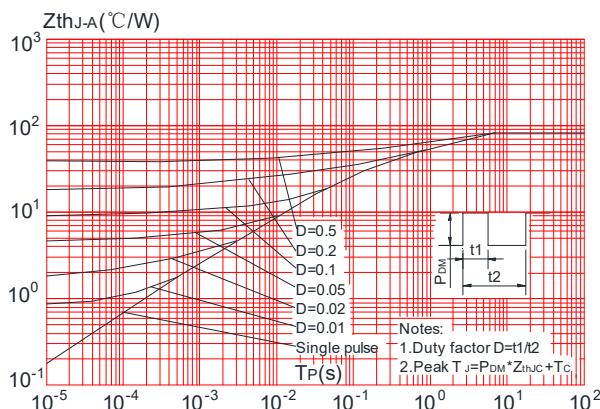
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



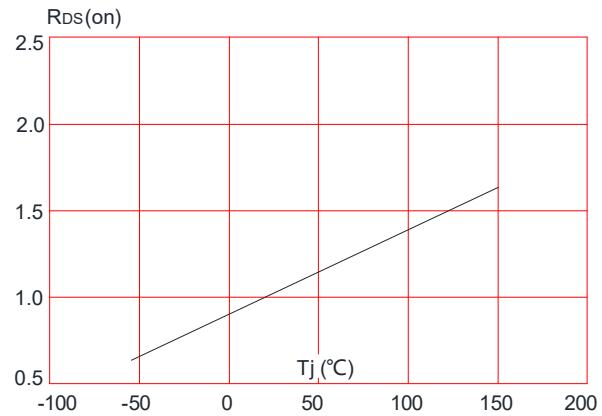
**Figure 9:** Maximum Safe Operating Area



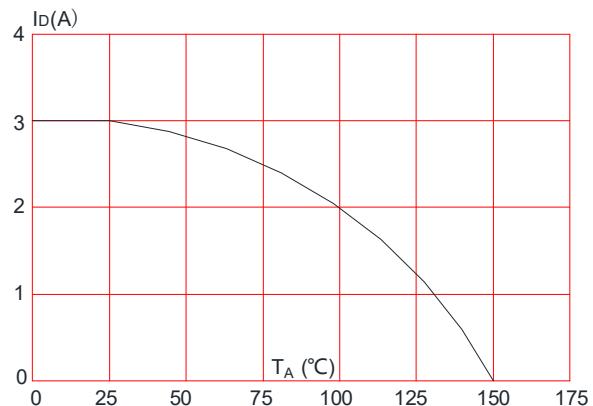
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



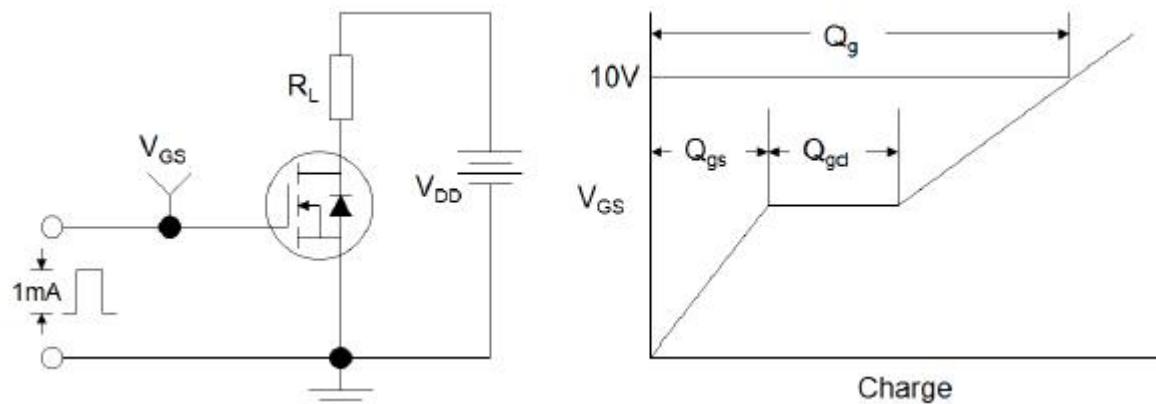
**Test Circuit**

Figure 1: Gate Charge Test Circuit &amp; Waveform

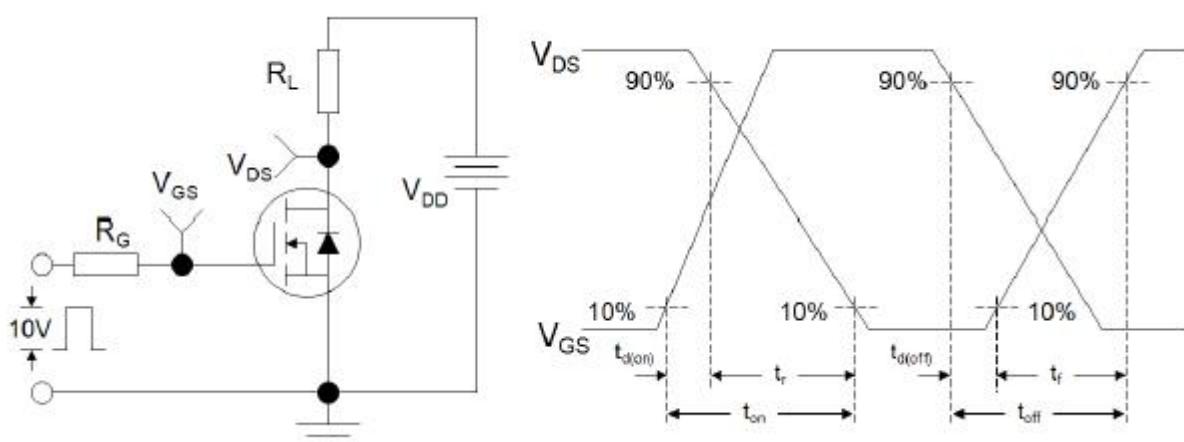


Figure 2: Resistive Switching Test Circuit &amp; Waveforms

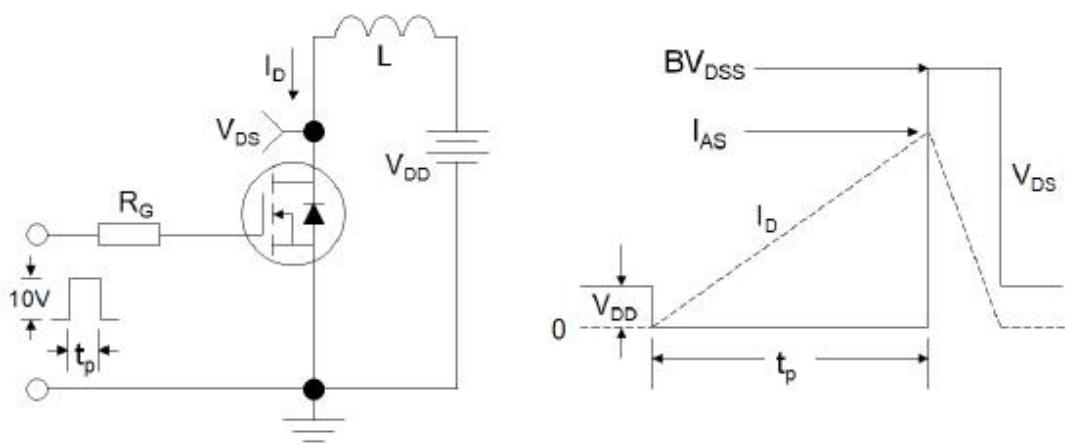
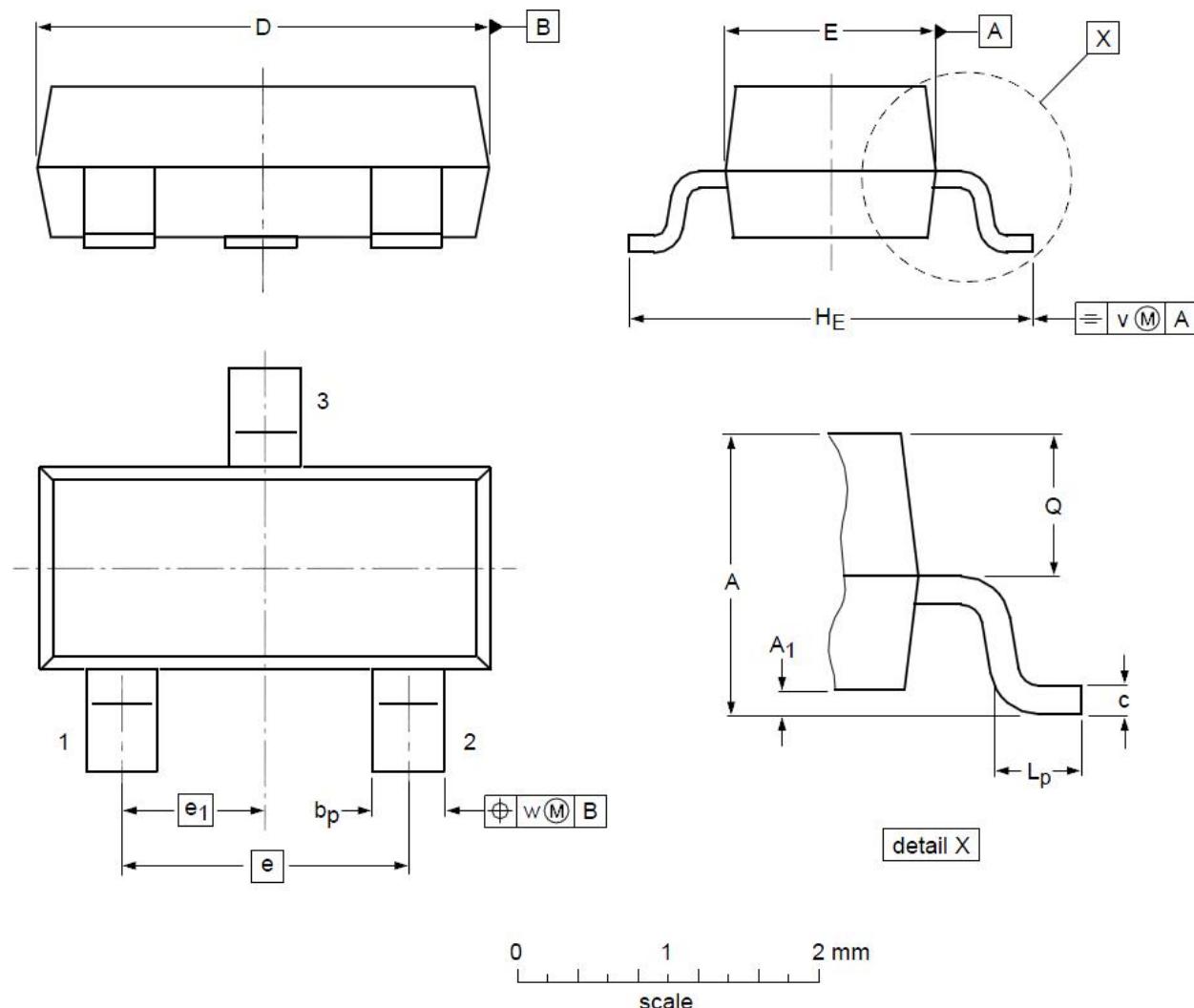


Figure 3: Unclamped Inductive Switching Test Circuit &amp; Waveforms

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## Package Mechanical Data-SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°